

**Amendments to the Claims:**

This listing of claims will replace all prior versions, and listings, of claims in the application:

**Listing of Claims:**

1. (Currently Amended) A semiconductor integrated circuit device comprising a driver circuit, a first long-distance wiring connected to the driver circuit, and a plurality of gate circuits connected over the entire length of the first long-distance wiring, so that an input signal (VIN) is received by the plurality of gate circuits via the driver circuit and the first long-distance wiring,

wherein a node arranged in the vicinity of an input terminal of the gate circuit ~~connected-to-an-end-of~~ located furthest away on the first long-distance wiring ~~from~~ an output of the driver circuit and an input terminal of the driver circuit are connected through a second long-distance wiring and a speed-increasing circuit.

2. (Original) The semiconductor integrated circuit device as claimed in Claim 1, wherein the speed-increasing circuit includes a PMOS transistor.

3. (Original) The semiconductor integrated circuit device as claimed in Claim 1, wherein the speed-increasing circuit includes an NMOS transistor and a buffer circuit is inserted at an input side of the second-long distance wiring.

4. (Original) The semiconductor integrated circuit device as claimed in Claim 1, wherein the speed-increasing circuit includes a CMOS inverter having a PMOS

transistor and an NMOS transistor.

5. (Original) The semiconductor integrated circuit device as claimed in Claim 1, wherein a plurality of speed-increasing circuits are additionally inserted between an intermediate position of the second long-distance wiring and the vicinity of the input terminal of the gate circuit connected to a position corresponding to that intermediate position.

6. (Previously Presented) The semiconductor integrated circuit device as claimed in Claim 1, wherein a plurality of buffer circuits are inserted at the input side of the second long-distance wiring.

7. (Original) The semiconductor integrated circuit device as claimed in Claim 1, wherein a buffer circuit is inserted at the input side of the second long-distance wiring, and a buffer circuit is inserted at the output side of the second long-distance wiring.

8. (Previously Presented) The semiconductor integrated circuit device as claimed in Claim 1, wherein the input signal (VIN) is realized by a word line selecting signal; the driver circuit is realized by a word line driver; the first long-distance wiring is realized by a word line (WL); and the gate circuits are realized by memory cells.

9. (Previously Presented) The semiconductor integrated circuit device as claimed in Claim 1, wherein the input signal (VIN) is realized by a clock input signal (VCK); the driver circuit is realized by a clock driver; and the gate circuits are realized by flip-flop circuits.

10. (Previously Presented) A semiconductor integrated circuit device comprising a driver circuit, a first long-distance wiring connected to the driver circuit, and a plurality of gate circuits connected over an entire length of the first long-distance wiring, so that an input signal (VIN) is received by the plurality of gate circuits via the driver circuit and the first long-distance wiring,

wherein a node arranged in a vicinity of an input terminal of the gate circuit connected to an end of the first long-distance wiring and an input terminal of the driver circuit are connected through a second long-distance wiring and a speed-increasing circuit, wherein the speed-increasing circuit includes an NMOS transistor and a buffer circuit is inserted at an input side of the second long-distance wiring.

11. (Previously Presented) A semiconductor integrated circuit device comprising a driver circuit, a first long-distance wiring connected to the driver circuit, and a plurality of gate circuits connected over an entire length of the first long-distance wiring, so that an input signal (VIN) is received by the plurality of gate circuits via the driver circuit and the first long-distance wiring,

wherein a node arranged in a vicinity of an input terminal of the gate circuit connected to an end of the first long-distance wiring and an input terminal of the driver circuit are connected through a second long-distance wiring and a speed-increasing circuit, wherein the speed-increasing circuit includes a CMOS inverter having a PMOS transistor and an NMOS transistor.

12. (Previously Presented) A semiconductor integrated circuit device comprising a driver circuit, a first long-distance wiring connected to the driver circuit,

and a plurality of gate circuits connected over an entire length of the first long-distance wiring, so that an input signal (VIN) is received by the plurality of gate circuits via the driver circuit and the first long-distance wiring,

wherein a node arranged in a vicinity of an input terminal of the gate circuit connected to an end of the first long-distance wiring and an input terminal of the driver circuit are connected through a second long-distance wiring and a speed-increasing circuit, wherein a plurality of speed-increasing circuits are additionally inserted between an intermediate position of the second long-distance wiring and the vicinity of the input terminal of the gate circuit connected to a position corresponding to the intermediate position.

13. (Previously Presented) A semiconductor integrated circuit device comprising a driver circuit, a first long-distance wiring connected to the driver circuit, and a plurality of gate circuits connected over an entire length of the first long-distance wiring, so that an input signal (VIN) is received by the plurality of gate circuits via the driver circuit and the first long-distance wiring,

wherein a node arranged in a vicinity of an input terminal of the gate circuit connected to an end of the first long-distance wiring and an input terminal of the driver circuit are connected through a second long-distance wiring and a speed-increasing circuit, wherein a plurality of buffer circuits are inserted at the input side of the second long-distance wiring.

14. (Previously Presented) A semiconductor integrated circuit device comprising a driver circuit, a first long-distance wiring connected to the driver circuit,

and a plurality of gate circuits connected over an entire length of the first long-distance wiring, so that an input signal (VIN) is received by the plurality of gate circuits via the driver circuit and the first long-distance wiring,

wherein a node arranged in a vicinity of an input terminal of the gate circuit connected to an end of the first long-distance wiring and an input terminal of the driver circuit are connected through a second long-distance wiring and a speed-increasing circuit, wherein a buffer circuit is inserted at the input side of the second long-distance wiring, and a buffer circuit is inserted at the output side of the second long-distance wiring.

15. (Previously Presented) A semiconductor integrated circuit device comprising a driver circuit, a first long-distance wiring connected to the driver circuit, and a plurality of gate circuits connected over an entire length of the first long-distance wiring, so that an input signal (VIN) is received by the plurality of gate circuits via the driver circuit and the first long-distance wiring,

wherein a node arranged in a vicinity of an input terminal of the gate circuit connected to an end of the first long-distance wiring and an input terminal of the driver circuit are connected through a second long-distance wiring and a speed-increasing circuit, wherein the input signal (VIN) is realized by a clock input signal (VCK); the driver circuit is realized by a clock driver; and the gate circuits are realized by flip-flop circuits.

16. (Previously Presented) A semiconductor integrated circuit device comprising a driver circuit, a first wiring coupled to the driver circuit, a plurality of

gate circuits coupled over an entire length of the first wiring so that an input signal is received by the plurality of gate circuits via the driver circuit and the first wiring, and a second wiring and a speed-increasing circuit coupled between a first node and a second node, said first node being at an input terminal of the driver circuit and said second node being in a vicinity of an input terminal of one of the gate circuits coupled to an end of the first wiring.

17. (Previously Presented) The semiconductor integrated circuit device as claimed in claim 16, wherein the speed-increasing circuit includes a PMOS transistor.

18. (Previously Presented) The semiconductor integrated circuit device as claimed in claim 16, wherein the speed-increasing circuit includes an NMOS transistor and a buffer circuit is inserted at an input side of the second wiring.

19. (Previously Presented) The semiconductor integrated circuit device as claimed in claim 16, wherein the speed-increasing circuit includes a CMOS inverter having a PMOS transistor and an NMOS transistor.

20. (Previously Presented) The semiconductor integrated circuit device as claimed in claim 16, wherein a plurality of speed-increasing circuits are additionally inserted between an intermediate position of the second wiring and the vicinity of the input terminal of the gate circuit connected to a position corresponding to the intermediate position.

21. (Previously Presented) The semiconductor integrated circuit device as claimed in claim 16, wherein a plurality of buffer circuits are inserted at the input side of the second wiring.

22. (Previously Presented) The semiconductor integrated circuit device as claimed in claim 16, wherein a buffer circuit is inserted at the input side of the second wiring.

23. (Previously Presented) The semiconductor integrated circuit device as claimed in claim 16, wherein the input signal is realized by a word line selecting signal; the driver circuit is realized by a word line driver; the first wiring is realized by a word line; and the gate circuits are realized by memory cells.

24. (Previously Presented) The semiconductor integrated circuit device as claimed in claim 16, wherein the input signal is realized by a clock input signal; the driver circuit is realized by a clock driver; and the gate circuits are realized by flip-flop circuits.

25. (Previously Presented) The semiconductor integrated circuit device as claimed in Claim 1, wherein the input signal (VIN) is a non-clock input signal.

26. (Previously Presented) The semiconductor integrated circuit device as claimed in Claim 1, wherein the speed-increasing circuit is driven by a signal from the second long-distance wiring when the input signal changes from a first state to a

second state and the speed-increasing circuit is driven by a signal from the first long-distance wiring when the input signal changes from the second state to the first state.

27. (Previously Presented) The semiconductor integrated circuit device as claimed in Claim 1, wherein a wiring delay time of the first long-distance wiring is different than a wiring delay time of the second long-distance wiring.